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Details

Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I ² C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	54
Program Memory Size	60KB (60K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-QFP
Supplier Device Package	64-QFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s08aw60cfuer

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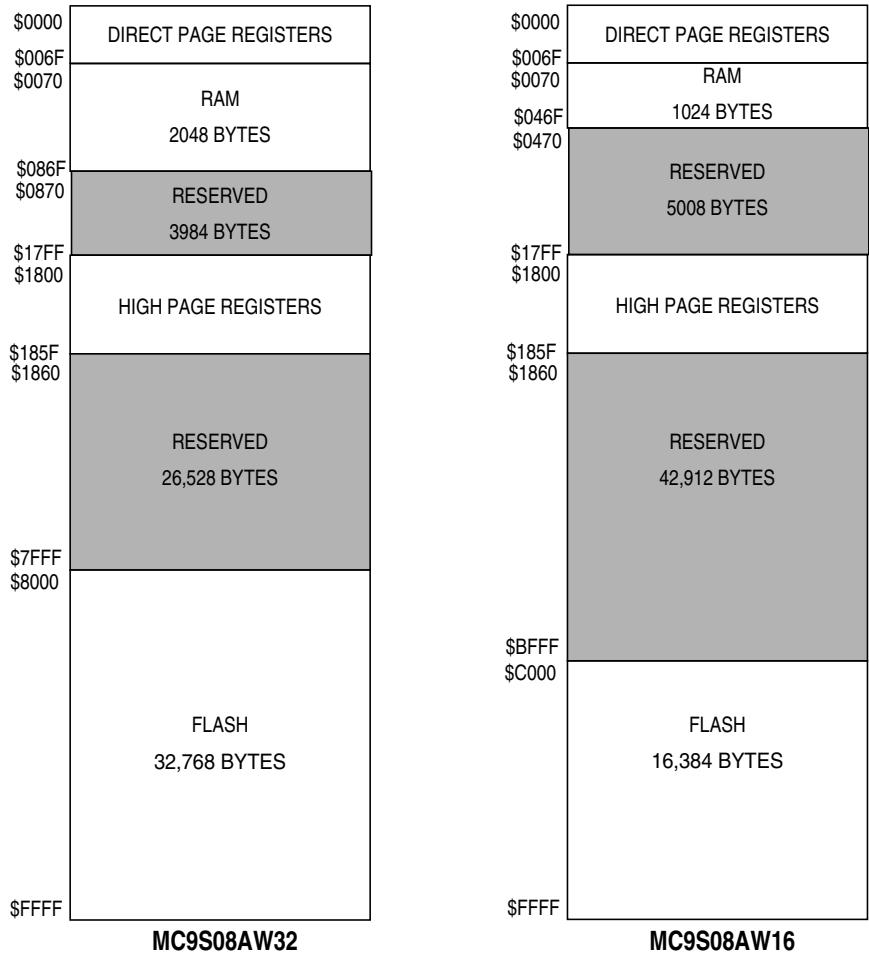


Figure 4-2. MC9S08AW32 and MC9S08AW16 Memory Map

4.6 FLASH Registers and Control Bits

The FLASH module has nine 8-bit registers in the high-page register space, three locations in the nonvolatile register space in FLASH memory which are copied into three corresponding high-page control registers at reset. There is also an 8-byte comparison key in FLASH memory. Refer to Table 4-3 and Table 4-4 for the absolute address assignments for all FLASH registers. This section refers to registers and control bits only by their names. A Freescale-provided equate or header file normally is used to translate these names into the appropriate absolute addresses.

4.6.1 FLASH Clock Divider Register (FCDIV)

Bit 7 of this register is a read-only status flag. Bits 6 through 0 may be read at any time but can be written only one time. Before any erase or programming operations are possible, write to this register to set the frequency of the clock for the nonvolatile memory system within acceptable limits.

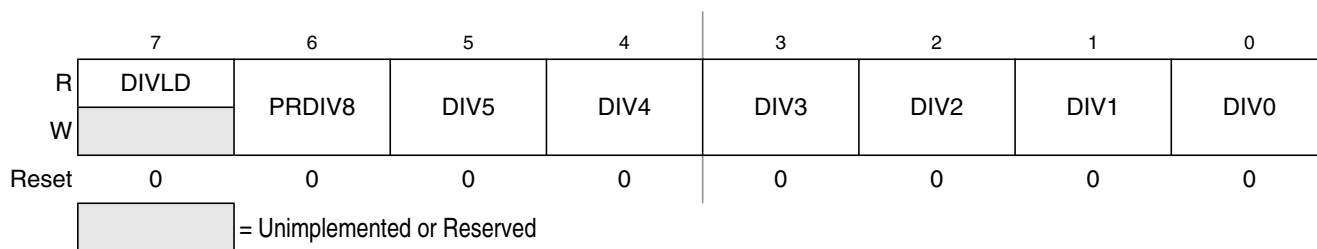


Figure 4-6. FLASH Clock Divider Register (FCDIV)

Table 4-6. FCDIV Register Field Descriptions

Field	Description
7 DIVLD	Divisor Loaded Status Flag — When set, this read-only status flag indicates that the FCDIV register has been written since reset. Reset clears this bit and the first write to this register causes this bit to become set regardless of the data written. 0 FCDIV has not been written since reset; erase and program operations disabled for FLASH. 1 FCDIV has been written since reset; erase and program operations enabled for FLASH.
6 PRDIV8	Prescale (Divide) FLASH Clock by 8 0 Clock input to the FLASH clock divider is the bus rate clock. 1 Clock input to the FLASH clock divider is the bus rate clock divided by 8.
5:0 DIV[5:0]	Divisor for FLASH Clock Divider — The FLASH clock divider divides the bus rate clock (or the bus rate clock divided by 8 if PRDIV8 = 1) by the value in the 6-bit DIV5:DIV0 field plus one. The resulting frequency of the internal FLASH clock must fall within the range of 200 kHz to 150 kHz for proper FLASH operations. Program/Erase timing pulses are one cycle of this internal FLASH clock which corresponds to a range of 5 μs to 6.7 μs. The automated programming logic uses an integer number of these pulses to complete an erase or program operation. See Equation 4-1, Equation 4-2, and Table 4-6.

$$\text{if PRDIV8} = 0 \text{ — } f_{\text{CLK}} = f_{\text{Bus}} \div ([\text{DIV5:DIV0}] + 1) \quad \text{Eqn. 4-1}$$

$$\text{if PRDIV8} = 1 \text{ — } f_{\text{CLK}} = f_{\text{Bus}} \div (8 \times ([\text{DIV5:DIV0}] + 1)) \quad \text{Eqn. 4-2}$$

Table 4-7 shows the appropriate values for PRDIV8 and DIV5:DIV0 for selected bus frequencies.

Table 4-12. FSTAT Register Field Descriptions

Field	Description
7 FCBEF	<p>FLASH Command Buffer Empty Flag — The FCBEF bit is used to launch commands. It also indicates that the command buffer is empty so that a new command sequence can be executed when performing burst programming. The FCBEF bit is cleared by writing a one to it or when a burst program command is transferred to the array for programming. Only burst program commands can be buffered.</p> <p>0 Command buffer is full (not ready for additional commands).</p> <p>1 A new burst program command may be written to the command buffer.</p>
6 FCCF	<p>FLASH Command Complete Flag — FCCF is set automatically when the command buffer is empty and no command is being processed. FCCF is cleared automatically when a new command is started (by writing 1 to FCBEF to register a command). Writing to FCCF has no meaning or effect.</p> <p>0 Command in progress</p> <p>1 All commands complete</p>
5 FPVIOL	<p>Protection Violation Flag — FPVIOL is set automatically when FCBEF is cleared to register a command that attempts to erase or program a location in a protected block (the erroneous command is ignored). FPVIOL is cleared by writing a 1 to FPVIOL.</p> <p>0 No protection violation.</p> <p>1 An attempt was made to erase or program a protected location.</p>
4 FACCERR	<p>Access Error Flag — FACCERR is set automatically when the proper command sequence is not obeyed exactly (the erroneous command is ignored), if a program or erase operation is attempted before the FCDIV register has been initialized, or if the MCU enters stop while a command was in progress. For a more detailed discussion of the exact actions that are considered access errors, see Section 4.4.5, “Access Errors.” FACCERR is cleared by writing a 1 to FACCERR. Writing a 0 to FACCERR has no meaning or effect.</p> <p>0 No access error.</p> <p>1 An access error has occurred.</p>
2 FBLANK	<p>FLASH Verified as All Blank (erased) Flag — FBLANK is set automatically at the conclusion of a blank check command if the entire FLASH array was verified to be erased. FBLANK is cleared by clearing FCBEF to write a new valid command. Writing to FBLANK has no meaning or effect.</p> <p>0 After a blank check command is completed and FCCF = 1, FBLANK = 0 indicates the FLASH array is not completely erased.</p> <p>1 After a blank check command is completed and FCCF = 1, FBLANK = 1 indicates the FLASH array is completely erased (all \$FF).</p>

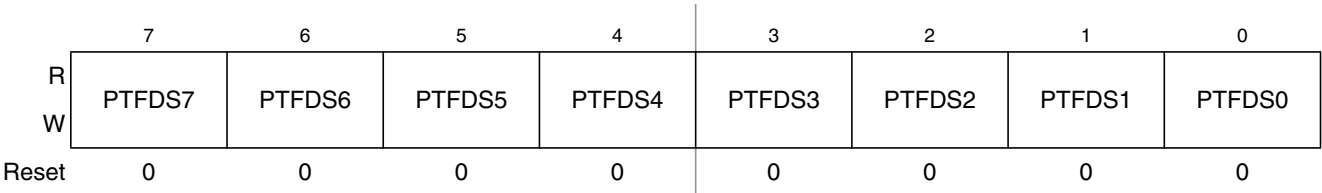


Figure 6-38. Output Drive Strength Selection for Port F (PTFDS)

Table 6-31. PTFDS Register Field Descriptions

Field	Description
7:0 PTFDS[7:0]	Output Drive Strength Selection for Port F Bits — Each of these control bits selects between low and high output drive for the associated PTF pin. 0 Low output drive enabled for port F bit n. 1 High output drive enabled for port F bit n.

6.7.14 Port G Pin Control Registers (PTGPE, PTGSE, PTGDS)

In addition to the I/O control, port G pins are controlled by the registers listed below.

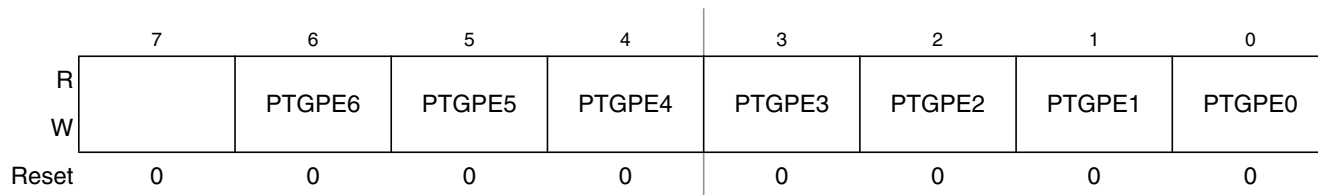


Figure 6-41. Internal Pullup Enable for Port G Bits (PTGPE)

Table 6-34. PTGPE Register Field Descriptions

Field	Description
6:0 PTGPE[6:0]	Internal Pullup Enable for Port G Bits — Each of these control bits determines if the internal pullup device is enabled for the associated PTG pin. For port G pins that are configured as outputs, these bits have no effect and the internal pullup devices are disabled. 0 Internal pullup device disabled for port G bit n. 1 Internal pullup device enabled for port G bit n.

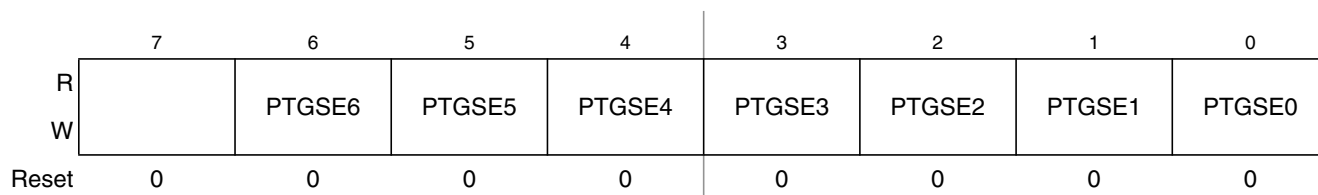


Figure 6-42. Output Slew Rate Control Enable for Port G Bits (PTGSE)

Table 6-35. PTGSE Register Field Descriptions

Field	Description
6:0 PTGSE[6:0]	Output Slew Rate Control Enable for Port G Bits — Each of these control bits determine whether output slew rate control is enabled for the associated PTG pin. For port G pins that are configured as inputs, these bits have no effect. 0 Output slew rate control disabled for port G bit n. 1 Output slew rate control enabled for port G bit n.

8.3.2 ICG Control Register 2 (ICGC2)

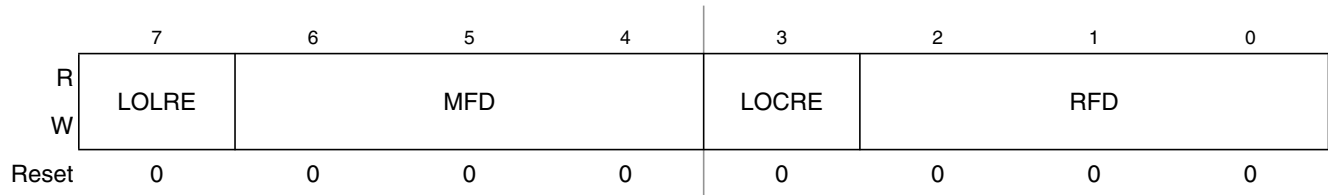


Figure 8-7. ICG Control Register 2 (ICGC2)

Table 8-2. ICGC2 Register Field Descriptions

Field	Description
7 LOLRE	Loss of Lock Reset Enable — The LOLRE bit determines what type of request is made by the ICG following a loss of lock indication. The LOLRE bit only has an effect when LOLS is set. 0 Generate an interrupt request on loss of lock. 1 Generate a reset request on loss of lock.
6:4 MFD	Multiplication Factor — The MFD bits control the programmable multiplication factor in the FLL loop. The value specified by the MFD bits establishes the multiplication factor (N) applied to the reference frequency. Writes to the MFD bits will not take effect if a previous write is not complete. Select a low enough value for N such that $f_{ICGDCLK}$ does not exceed its maximum specified value. 000 Multiplication factor = 4 001 Multiplication factor = 6 010 Multiplication factor = 8 011 Multiplication factor = 10 100 Multiplication factor = 12 101 Multiplication factor = 14 110 Multiplication factor = 16 111 Multiplication factor = 18
3 LOCRE	Loss of Clock Reset Enable — The LOCRE bit determines how the system manages a loss of clock condition. 0 Generate an interrupt request on loss of clock. 1 Generate a reset request on loss of clock.
2:0 RFD	Reduced Frequency Divider — The RFD bits control the value of the divider following the clock select circuitry. The value specified by the RFD bits establishes the division factor (R) applied to the selected output clock source. Writes to the RFD bits will not take effect if a previous write is not complete. 000 Division factor = 1 001 Division factor = 2 010 Division factor = 4 011 Division factor = 8 100 Division factor = 16 101 Division factor = 32 110 Division factor = 64 111 Division factor = 128

8.3.4 ICG Status Register 2 (ICGS2)

	7	6	5	4	3	2	1	0
R	0	0	0	0	0	0	0	DCOS
W								
Reset	0	0	0	0	0	0	0	0


 = Unimplemented or Reserved

Figure 8-9. ICG Status Register 2 (ICGS2)

Table 8-4. ICGS2 Register Field Descriptions

Field	Description
0 DCOS	DCO Clock Stable — The DCOS bit is set when the DCO clock (ICG2DCLK) is stable, meaning the count error has not changed by more than n_{unlock} for two consecutive samples and the DCO clock is not static. This bit is used when exiting off state if CLKS = X1 to determine when to switch to the requested clock mode. It is also used in self-clocked mode to determine when to start monitoring the DCO clock. This bit is cleared upon entering the off state. 0 DCO clock is unstable. 1 DCO clock is stable.

8.3.5 ICG Filter Registers (ICGFLTU, ICGFLTL)

	7	6	5	4	3	2	1	0
R	0	0	0	0	FLT			
W								
Reset	0	0	0	0	0	0	0	0


 = Unimplemented or Reserved

Figure 8-10. ICG Upper Filter Register (ICGFLTU)

Table 8-5. ICGFLTU Register Field Descriptions

Field	Description
3:0 FLT	Filter Value — The FLT bits indicate the current filter value, which controls the DCO frequency. The FLT bits are read only except when the CLKS bits are programmed to self-clocked mode (CLKS = 00). In self-clocked mode, any write to ICGFLTU updates the current 12-bit filter value. Writes to the ICGFLTU register will not affect FLT if a previous latch sequence is not complete.

10.5.3 Center-Aligned PWM Mode

This type of PWM output uses the up-/down-counting mode of the timer counter (CPWMS = 1). The output compare value in TPMxCnVH:TPMxCnVL determines the pulse width (duty cycle) of the PWM signal and the period is determined by the value in TPMxMODH:TPMxMODL.

TPMxMODH:TPMxMODL should be kept in the range of 0x0001 to 0x7FFF because values outside this range can produce ambiguous results. ELSnA will determine the polarity of the CPWM output.

$$\text{pulse width} = 2 \times (\text{TPMxCnVH:TPMxCnVL}) \quad \text{Eqn. 10-1}$$

$$\begin{aligned} \text{period} &= 2 \times (\text{TPMxMODH:TPMxMODL}); \\ &\text{for TPMxMODH:TPMxMODL} = 0x0001\text{--}0x7FFF \end{aligned} \quad \text{Eqn. 10-2}$$

If the channel value register TPMxCnVH:TPMxCnVL is zero or negative (bit 15 set), the duty cycle will be 0%. If TPMxCnVH:TPMxCnVL is a positive value (bit 15 clear) and is greater than the (nonzero) modulus setting, the duty cycle will be 100% because the duty cycle compare will never occur. This implies the usable range of periods set by the modulus register is 0x0001 through 0x7FFE (0x7FFF if generation of 100% duty cycle is not necessary). This is not a significant limitation because the resulting period is much longer than required for normal applications.

TPMxMODH:TPMxMODL = 0x0000 is a special case that should not be used with center-aligned PWM mode. When CPWMS = 0, this case corresponds to the counter running free from 0x0000 through 0xFFFF, but when CPWMS = 1 the counter needs a valid match to the modulus register somewhere other than at 0x0000 in order to change directions from up-counting to down-counting.

Figure 10-12 shows the output compare value in the TPM channel registers (multiplied by 2), which determines the pulse width (duty cycle) of the CPWM signal. If ELSnA = 0, the compare match while counting up forces the CPWM output signal low and a compare match while counting down forces the output high. The counter counts up until it reaches the modulo setting in TPMxMODH:TPMxMODL, then counts down until it reaches zero. This sets the period equal to two times TPMxMODH:TPMxMODL.

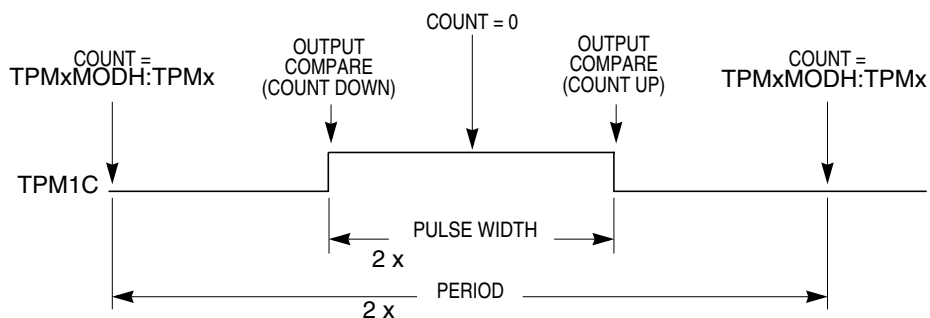


Figure 10-12. CPWM Period and Pulse Width (ELSnA = 0)

Center-aligned PWM outputs typically produce less noise than edge-aligned PWMs because fewer I/O pin transitions are lined up at the same system clock edge. This type of PWM is also required for some types of motor drives.

Because the HCS08 is a family of 8-bit MCUs, the settings in the timer channel registers are buffered to ensure coherent 16-bit updates and to avoid unexpected PWM pulse widths. Writes to any of the registers, TPMxMODH, TPMxMODL, TPMxCnVH, and TPMxCnVL, actually write to buffer registers. Values are

10.6.3 Channel Event Interrupt Description

The meaning of channel interrupts depends on the current mode of the channel (input capture, output compare, edge-aligned PWM, or center-aligned PWM).

When a channel is configured as an input capture channel, the ELSnB:ELSnA control bits select rising edges, falling edges, any edge, or no edge (off) as the edge that triggers an input capture event. When the selected edge is detected, the interrupt flag is set. The flag is cleared by the 2-step sequence described in Section 10.6.1, “Clearing Timer Interrupt Flags.”

When a channel is configured as an output compare channel, the interrupt flag is set each time the main timer counter matches the 16-bit value in the channel value register. The flag is cleared by the 2-step sequence described in Section 10.6.1, “Clearing Timer Interrupt Flags.”

10.6.4 PWM End-of-Duty-Cycle Events

For channels that are configured for PWM operation, there are two possibilities:

- When the channel is configured for edge-aligned PWM, the channel flag is set when the timer counter matches the channel value register that marks the end of the active duty cycle period.
- When the channel is configured for center-aligned PWM, the timer count matches the channel value register twice during each PWM cycle. In this CPWM case, the channel flag is set at the start and at the end of the active duty cycle, which are the times when the timer counter matches the channel value register.

The flag is cleared by the 2-step sequence described in Section 10.6.1, “Clearing Timer Interrupt Flags.”

12.4 Functional Description

An SPI transfer is initiated by checking for the SPI transmit buffer empty flag (SPTEF = 1) and then writing a byte of data to the SPI data register (SPI1D) in the master SPI device. When the SPI shift register is available, this byte of data is moved from the transmit data buffer to the shifter, SPTEF is set to indicate there is room in the buffer to queue another transmit character if desired, and the SPI serial transfer starts.

During the SPI transfer, data is sampled (read) on the MISO pin at one SPSCCK edge and shifted, changing the bit value on the MOSI pin, one-half SPSCCK cycle later. After eight SPSCCK cycles, the data that was in the shift register of the master has been shifted out the MOSI pin to the slave while eight bits of data were shifted in the MISO pin into the master's shift register. At the end of this transfer, the received data byte is moved from the shifter into the receive data buffer and SPRF is set to indicate the data can be read by reading SPI1D. If another byte of data is waiting in the transmit buffer at the end of a transfer, it is moved into the shifter, SPTEF is set, and a new transfer is started.

Normally, SPI data is transferred most significant bit (MSB) first. If the least significant bit first enable (LSBFE) bit is set, SPI data is shifted LSB first.

When the SPI is configured as a slave, its \overline{SS} pin must be driven low before a transfer starts and \overline{SS} must stay low throughout the transfer. If a clock format where CPHA = 0 is selected, \overline{SS} must be driven to a logic 1 between successive transfers. If CPHA = 1, \overline{SS} may remain low between successive transfers. See Section 12.4.1, "SPI Clock Formats" for more details.

Because the transmitter and receiver are double buffered, a second byte, in addition to the byte currently being shifted out, can be queued into the transmit data buffer, and a previously received character can be in the receive data buffer while a new character is being shifted in. The SPTEF flag indicates when the transmit buffer has room for a new character. The SPRF flag indicates when a received character is available in the receive data buffer. The received character must be read out of the receive buffer (read SPI1D) before the next transfer is finished or a receive overrun error results.

In the case of a receive overrun, the new data is lost because the receive buffer still held the previous character and was not ready to accept the new data. There is no indication for such an overrun condition so the application system designer must ensure that previous data has been read from the receive buffer before a new transfer is initiated.

12.4.1 SPI Clock Formats

To accommodate a wide variety of synchronous serial peripherals from different manufacturers, the SPI system has a clock polarity (CPOL) bit and a clock phase (CPHA) control bit to select one of four clock formats for data transfers. CPOL selectively inserts an inverter in series with the clock. CPHA chooses between two different clock phase relationships between the clock and data.

Figure 12-10 shows the clock formats when CPHA = 1. At the top of the figure, the eight bit times are shown for reference with bit 1 starting at the first SPSCCK edge and bit 8 ending one-half SPSCCK cycle after the sixteenth SPSCCK edge. The MSB first and LSB first lines show the order of SPI data bits depending on the setting in LSBFE. Both variations of SPSCCK polarity are shown, but only one of these waveforms applies for a specific transfer, depending on the value in CPOL. The SAMPLE IN waveform applies to the MOSI input of a slave or the MISO input of a master. The MOSI waveform applies to the MOSI output

13.4.1.1 START Signal

When the bus is free; i.e., no master device is engaging the bus (both SCL and SDA lines are at logical high), a master may initiate communication by sending a START signal. As shown in Figure 13-8, a START signal is defined as a high-to-low transition of SDA while SCL is high. This signal denotes the beginning of a new data transfer (each data transfer may contain several bytes of data) and brings all slaves out of their idle states.

13.4.1.2 Slave Address Transmission

The first byte of data transferred immediately after the START signal is the slave address transmitted by the master. This is a seven-bit calling address followed by a R/W bit. The R/W bit tells the slave the desired direction of data transfer.

1 = Read transfer, the slave transmits data to the master.

0 = Write transfer, the master transmits data to the slave.

Only the slave with a calling address that matches the one transmitted by the master will respond by sending back an acknowledge bit. This is done by pulling the SDA low at the 9th clock (see Figure 13-8).

No two slaves in the system may have the same address. If the IIC module is the master, it must not transmit an address that is equal to its own slave address. The IIC cannot be master and slave at the same time.

However, if arbitration is lost during an address cycle, the IIC will revert to slave mode and operate correctly even if it is being addressed by another master.

13.4.1.3 Data Transfer

Before successful slave addressing is achieved, the data transfer can proceed byte-by-byte in a direction specified by the R/W bit sent by the calling master.

All transfers that come after an address cycle are referred to as data transfers, even if they carry sub-address information for the slave device

Each data byte is 8 bits long. Data may be changed only while SCL is low and must be held stable while SCL is high as shown in Figure 13-8. There is one clock pulse on SCL for each data bit, the MSB being transferred first. Each data byte is followed by a 9th (acknowledge) bit, which is signalled from the receiving device. An acknowledge is signalled by pulling the SDA low at the ninth clock. In summary, one complete data transfer needs nine clock pulses.

If the slave receiver does not acknowledge the master in the 9th bit time, the SDA line must be left high by the slave. The master interprets the failed acknowledge as an unsuccessful data transfer.

If the master receiver does not acknowledge the slave transmitter after a data byte transmission, the slave interprets this as an end of data transfer and releases the SDA line.

In either case, the data transfer is aborted and the master does one of two things:

- Relinquishes the bus by generating a STOP signal.
- Commences a new calling by generating a repeated START signal.

14.7.2 Sources of Error

Several sources of error exist for A/D conversions. These are discussed in the following sections.

14.7.2.1 Sampling Error

For proper conversions, the input must be sampled long enough to achieve the proper accuracy. Given the maximum input resistance of approximately $7\text{k}\Omega$ and input capacitance of approximately 5.5 pF , sampling to within $1/4\text{LSB}$ (at 10-bit resolution) can be achieved within the minimum sample window (3.5 cycles @ 8 MHz maximum ADCK frequency) provided the resistance of the external analog source (R_{AS}) is kept below $5\text{ k}\Omega$.

Higher source resistances or higher-accuracy sampling is possible by setting ADLSMP (to increase the sample window to 23.5 cycles) or decreasing ADCK frequency to increase sample time.

14.7.2.2 Pin Leakage Error

Leakage on the I/O pins can cause conversion error if the external analog source resistance (R_{AS}) is high. If this error cannot be tolerated by the application, keep R_{AS} lower than $V_{DDAD} / (2^N \cdot I_{LEAK})$ for less than $1/4\text{LSB}$ leakage error ($N = 8$ in 8-bit mode or 10 in 10-bit mode).

14.7.2.3 Noise-Induced Errors

System noise which occurs during the sample or conversion process can affect the accuracy of the conversion. The ADC accuracy numbers are guaranteed as specified only if the following conditions are met:

- There is a $0.1\text{ }\mu\text{F}$ low-ESR capacitor from V_{REFH} to V_{REFL} .
- There is a $0.1\text{ }\mu\text{F}$ low-ESR capacitor from V_{DDAD} to V_{SSAD} .
- If inductive isolation is used from the primary supply, an additional $1\text{ }\mu\text{F}$ capacitor is placed from V_{DDAD} to V_{SSAD} .
- V_{SSAD} (and V_{REFL} , if connected) is connected to V_{SS} at a quiet point in the ground plane.
- Operate the MCU in wait or stop3 mode before initiating (hardware triggered conversions) or immediately after initiating (hardware or software triggered conversions) the ADC conversion.
 - For software triggered conversions, immediately follow the write to the ADC1SC1 with a WAIT instruction or STOP instruction.
 - For stop3 mode operation, select ADACK as the clock source. Operation in stop3 reduces V_{DD} noise but increases effective conversion time due to stop recovery.
- There is no I/O switching, input or output, on the MCU during the conversion.

There are some situations where external system activity causes radiated or conducted noise emissions or excessive V_{DD} noise is coupled into the ADC. In these situations, or when the MCU cannot be placed in wait or stop3 or I/O activity cannot be halted, these recommended actions may reduce the effect of noise on the accuracy:

- Place a $0.01\text{ }\mu\text{F}$ capacitor (C_{AS}) on the selected input channel to V_{REFL} or V_{SSAD} (this will improve noise issues but will affect sample rate based on the external analog source resistance).

- Average the result by converting the analog input many times in succession and dividing the sum of the results. Four samples are required to eliminate the effect of a 1LSB, one-time error.
- Reduce the effect of synchronous noise by operating off the asynchronous clock (ADACK) and averaging. Noise that is synchronous to ADCK cannot be averaged out.

14.7.2.4 Code Width and Quantization Error

The ADC quantizes the ideal straight-line transfer function into 1024 steps (in 10-bit mode). Each step ideally has the same height (1 code) and width. The width is defined as the delta between the transition points to one code and the next. The ideal code width for an N bit converter (in this case N can be 8 or 10), defined as 1LSB, is:

$$1\text{LSB} = (V_{\text{REFH}} - V_{\text{REFL}}) / 2^N \quad \text{Eqn. 14-2}$$

There is an inherent quantization error due to the digitization of the result. For 8-bit or 10-bit conversions the code will transition when the voltage is at the midpoint between the points where the straight line transfer function is exactly represented by the actual transfer function. Therefore, the quantization error will be $\pm 1/2\text{LSB}$ in 8- or 10-bit mode. As a consequence, however, the code width of the first (\$000) conversion is only $1/2\text{LSB}$ and the code width of the last (\$FF or \$3FF) is 1.5LSB .

14.7.2.5 Linearity Errors

The ADC may also exhibit non-linearity of several forms. Every effort has been made to reduce these errors but the system should be aware of them because they affect overall accuracy. These errors are:

- Zero-scale error (E_{ZS}) (sometimes called offset) — This error is defined as the difference between the actual code width of the first conversion and the ideal code width ($1/2\text{LSB}$). Note, if the first conversion is \$001, then the difference between the actual \$001 code width and its ideal (1LSB) is used.
- Full-scale error (E_{FS}) — This error is defined as the difference between the actual code width of the last conversion and the ideal code width (1.5LSB). Note, if the last conversion is \$3FE, then the difference between the actual \$3FE code width and its ideal (1LSB) is used.
- Differential non-linearity (DNL) — This error is defined as the worst-case difference between the actual code width and the ideal code width for all conversions.
- Integral non-linearity (INL) — This error is defined as the highest-value the (absolute value of the) running sum of DNL achieves. More simply, this is the worst-case difference of the actual transition voltage to a given code and its corresponding ideal transition voltage, for all codes.
- Total unadjusted error (TUE) — This error is defined as the difference between the actual transfer function and the ideal straight-line transfer function, and therefore includes all forms of error.

14.7.2.6 Code Jitter, Non-Monotonicity and Missing Codes

Analog-to-digital converters are susceptible to three special forms of error. These are code jitter, non-monotonicity, and missing codes.

Code jitter is when, at certain points, a given input voltage converts to one of two values when sampled repeatedly. Ideally, when the input voltage is infinitesimally smaller than the transition voltage, the

15.4.3.8 Debug Trigger Register (DBGT)

This register can be read any time, but may be written only if ARM = 0, except bits 4 and 5 are hard-wired to 0s.

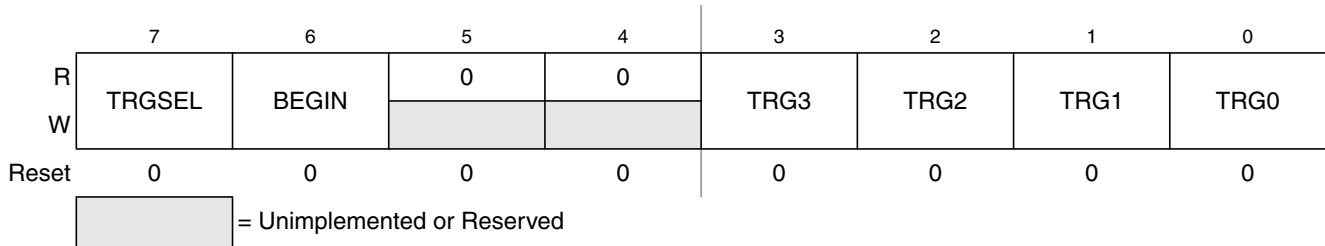
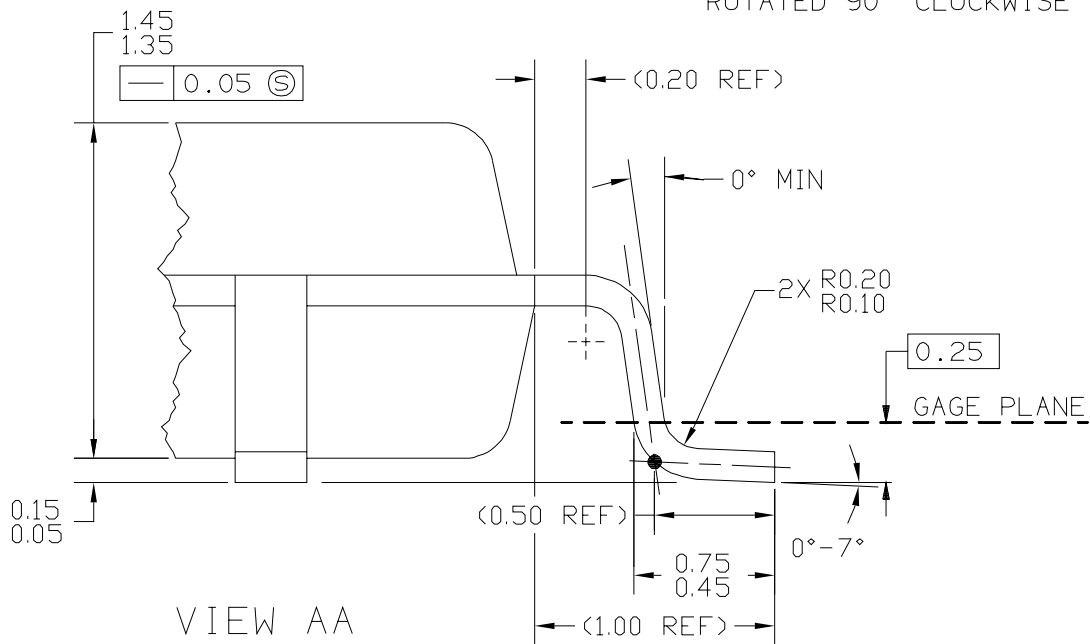
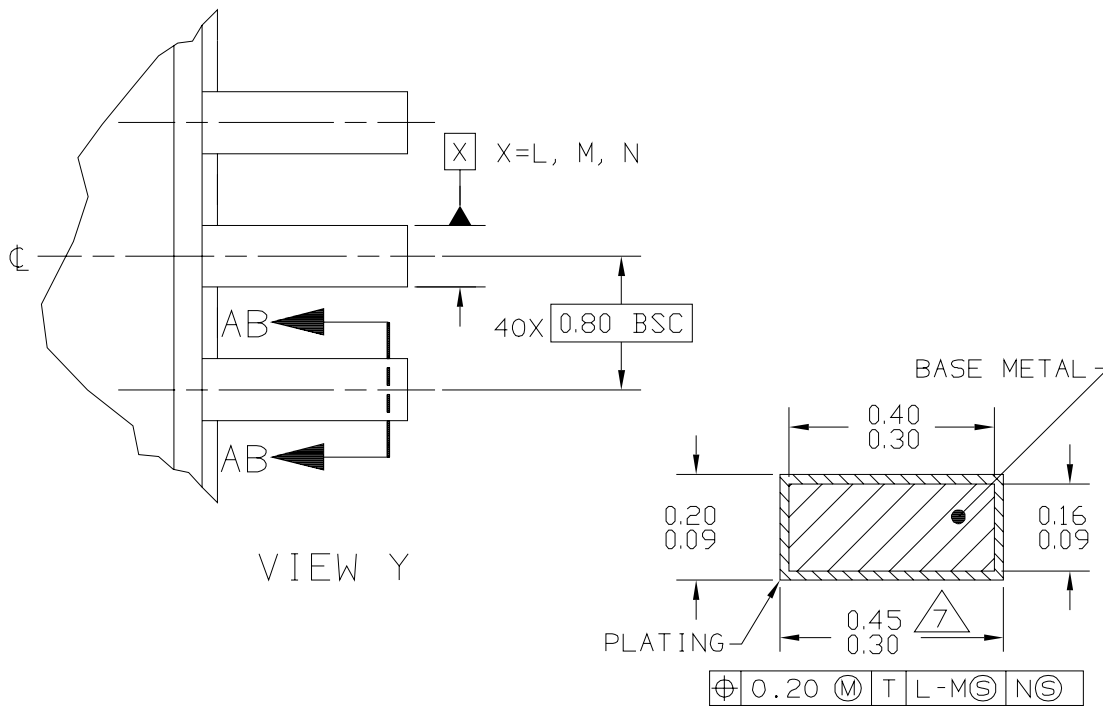


Figure 15-8. Debug Trigger Register (DBGT)

Table 15-5. DBGT Register Field Descriptions

Field	Description
7 TRGSEL	Trigger Type — Controls whether the match outputs from comparators A and B are qualified with the opcode tracking logic in the debug module. If TRGSEL is set, a match signal from comparator A or B must propagate through the opcode tracking logic and a trigger event is only signalled to the FIFO logic if the opcode at the match address is actually executed. 0 Trigger on access to compare address (force) 1 Trigger if opcode at compare address is executed (tag)
6 BEGIN	Begin/End Trigger Select — Controls whether the FIFO starts filling at a trigger or fills in a circular manner until a trigger ends the capture of information. In event-only trigger modes, this bit is ignored and all debug runs are assumed to be begin traces. 0 Data stored in FIFO until trigger (end trace) 1 Trigger initiates data storage (begin trace)
3:0 TRG[3:0]	Select Trigger Mode — Selects one of nine triggering modes, as described below. 0000 A-only 0001 A OR B 0010 A Then B 0011 Event-only B (store data) 0100 A then event-only B (store data) 0101 A AND B data (full mode) 0110 A AND NOT B data (full mode) 0111 Inside range: $A \leq \text{address} \leq B$ 1000 Outside range: $\text{address} < A$ or $\text{address} > B$ 1001 – 1111 (No trigger)



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		CASE NUMBER: 824D-02		26 FEB 2007
		STANDARD: JEDEC MS-026 BCB		



NOTES:

- 1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M–1994.
- 2. CONTROLLING DIMENSION: MILLIMETER
- 3. DATUM PLANE H IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
- 4. DATUMS L, M AND N TO BE DETERMINED AT DATUM PLANE H.

5. DIMENSIONS TO BE DETERMINED AT SEATING PLANE T.

6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.

7. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE DIMENSION TO EXCEED 0.53. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07.

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